

Customer No.: 31561
Application No.: 10/605,056
Docket No.: 9388-US-PA

REMARKS

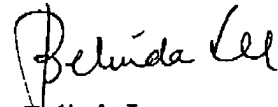
Applicant would like to elect Group I, claims 1-13, drawn to a semiconductor package method, classified in class 438, subclass 110. Please cancel the following two groups without waiver, prejudice or disclaimer:

1. Group II, claims 14-22, drawn to a semiconductor package, classified in class 257, subclass 690;
2. Group III, claims 23-31, drawn to a semiconductor substrate process, classified in class 438, subclass 612.

If the Examiner believes that a telephone conference would expedite the examination of the above-identified patent application, the Examiner is invited to call the undersigned.

Respectfully submitted,

Date: Dec. 28, 2004



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